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TITLE : SOLDER ALLOY FOR CONNECTOR CONTACT

ABSTRACT : PURPOSE: To provide improvement in the contact stability, etc. of a connector by adding specific % of silver to a solder alloy consisting of tin and indium contg. specific weight % of indium.

CONSTITUTION: The silver corresponding to 0.2~30% in total quantity is added to the solder alloy contg. 41~93% indium and the balance tin. The Knoop hardness of the alloy eutectic structure increases with an increase in the addition of the silver. The hardness is increased 3 times in the case of 30%. The instability of the contact between a connector pin and a solder bath occurs in the deficient hardness of the solder alloy. The hardness of the solder bath increases when 0.2~30% silver by the total weight is added thereto. The contact stability is thus improved and the contact resistance is decreased.

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